LNA2901L

GaAs Infrared Light Emitting Diode

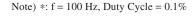
For optical control systems

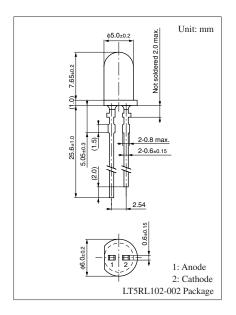
■ Features

- High-power output, high-efficiency: $I_e = 9 \text{ mW/sr (min.)}$
- Emitted light spectrum suited for silicon photodetectors
- Transparent epoxy resin package
- Long lead-wire type

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	3	V
Forward current	I_{F}	50	mA
Pulse forward current *	I_{FP}	1	A
Power dissipation	P_{D}	160	mW
Operating ambient temperature	T_{opr}	-25 to +85	°C
Storage temperature	T_{stg}	-40 to +100	°C





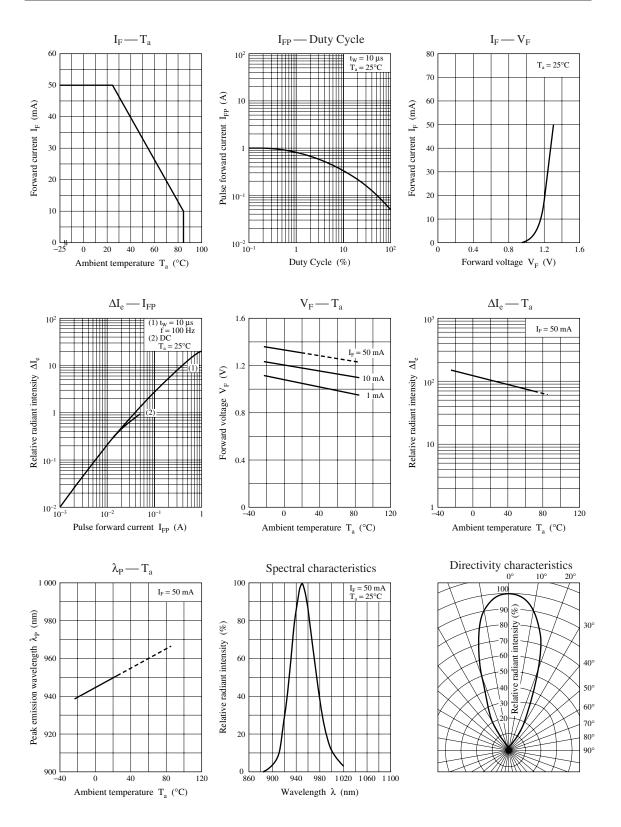
\blacksquare Electrical-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\rm F}$	$I_F = 50 \text{ mA}$		1.3	1.5	V
Pulse forward voltage *	V _{FP}	$I_{FP} = 1 A$			3	V
Reverse current	I_R	$V_R = 3 \text{ V}$			10	μΑ
Center radiant intensity	I _e	$I_F = 50 \text{ mA}$	9			mW/sr
Radiant power	Po	$I_F = 50 \text{ mA}$		12		mW
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 50 \text{ mA}$		950		nm
Spectral half band width	Δλ	$I_F = 50 \text{ mA}$		50		nm
Terminal capacitance	C _t	$V_R = 0 \text{ V, } f = 1 \text{ MHz}$		35		pF
Half-power angle	θ	The angle when the radiant power is halved		20		0

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Cutoff frequency: 1 MHz
$$f_C: 10 \times log \frac{P_O \text{ at } f = f_C}{P_O \text{ at } f = 50 \text{ kHz}} = -3$$

3. *: f = 100 Hz, Duty Cycle = 0.1%



Caution for Safety

⚠ DANGER

■ This product contains Gallium Arsenide (GaAs).

GaAs powder and vapor are hazardous to human health if inhaled or ingested. Do not burn, destroy, cut, cleave off, or chemically dissolve the product. Follow related laws and ordinances for disposal. The product should be excluded form general industrial waste or household garbage.

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